


MATERIAL DECLARATION SHEET



Material Number	SF-0603HI-M			
Product Line	Lead Free Multilayer High Inrush Current Chip Fuse			
Compliance Date	08/30/2017			
RoHS Compliant	YES	MSL	1	

No.	Construction Element (subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Ceramic Body	Glass Ceramic	1.586	Boron	7440-42-8	7.39%	5.3440%	72.314%
				Carbon	7440-44-0	2.11%	1.5258%	
				Aluminum	7429-90-5	18.65%	13.4866%	
				Silicon	7440-21-3	15.24%	11.0206%	
				Potassium	7440-09-7	0.53%	0.3833%	
				Oxygen	7782-44-7	56.08%	40.5537%	
2	Termination	Silver with Glass	0.3838	Silver	7440-22-4	92.25%	16.1437%	17.500%
				Oxygen	7782-44-7	2.23%	0.3903%	
				Zinc	7440-66-6	1.64%	0.2870%	
				Silicon	7440-21-3	0.10%	0.0175%	
				Bismuth	7440-69-9	3.78%	0.6615%	
3	Fuse Link	Silver	0.0094	Silver	7440-22-4	100%	0.4286%	0.429%
4	Plating	Nickel	0.21	Nickel	7440-02-0	100.00%	4.2996%	9.575%
		Tin		Tin	7440-31-5	100.00%	5.2753%	
5	Green Mark	Composite	0.0023	Oxygen	7782-44-7	56.09%	0.0584%	0.105%
				Aluminum	7429-90-5	18.35%	0.0191%	
				Silicon	7440-21-3	22.28%	0.0231%	
				Potassium	7440-09-7	0.92%	0.0010%	
				Chromium III	7440-47-3	2.36%	0.0024%	

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6	Masking Layer	Glass Ceramic	0.0017	Boron	7440-42-8	9.83%	0.0077%	0.078%
				Carbon	7440-44-0	1.81%	0.0014%	
				Aluminum	7429-90-5	16.85%	0.0132%	
				Silicon	7440-21-3	15.58%	0.0122%	
				Potassium	7440-09-7	0.53%	0.0004%	
				Oxygen	7782-44-7	55.40%	0.0433%	
				Total weight	2.1932			

This Document was updated on: 8-30-2017

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.